SN54F74, SN74F74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

SDFS046A - MARCH 1987 - REVISED OCTOBER 1993

 Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

These devices contain two independent positive-edge-triggered D-type flip-flops. A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

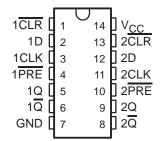
The SN54F74 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F74 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

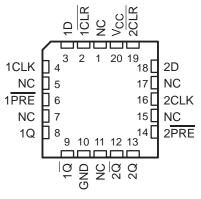
	INP	OUTI	PUTS		
PRE	CLR	CLK	D	Q	Ø
L	Н	Х	Χ	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	H [†]	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q ₀	\overline{Q}_0

[†] The output levels are not guaranteed to meet the minimum levels for V_{OH}. Furthermore, this configuration is nonstable; that is, it will not persist when PRE or CLR returns to its inactive (high) level.

SN54F74...J PACKAGE SN74F74...D OR N PACKAGE (TOP VIEW)



SN54F74 . . . FK PACKAGE (TOP VIEW)

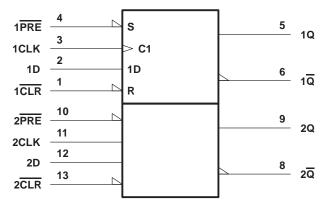


NC - No internal connection

SN54F74, SN74F74 **DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS** WITH CLEAR AND PRESET

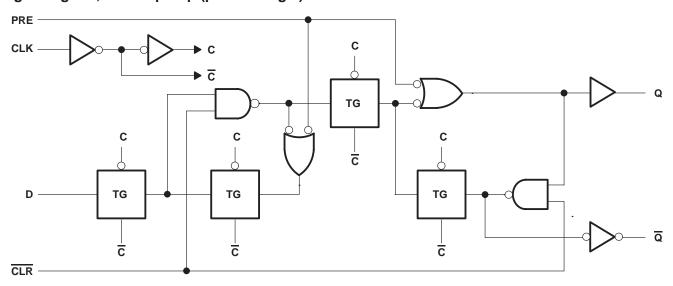
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logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	1.2 V to 7 V
Input current range	30 mA to 5 mA
Voltage range applied to any output in the high state	\dots -0.5 V to V _{CC}
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F74	. −55°C to 125°C
SN74F74	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.



SN54F74, SN74F74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET

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recommended operating conditions

		SN54F74		SN74F74			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ΙΙΚ	Input clamp current			-18			-18	mA
IOH	High-level output current			- 1			- 1	mA
lOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		,	SN54F74			SN74F74			
P#	ARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
٧ıK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
V/011		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		2.5	3.4		V	
VOH		$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA}$				2.7			٧	
VOL		$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5		0.3	0.5	V	
Ц		$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA	
Ι _{ΙΗ}		$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ	
1	Data, CLK	V _{CC} = 5.5 V,	V _I = 0.5 V			- 0.6			- 0.6	mA	
IIL	PRE or CLR	vCC = 5.5 v,	V = 0.5 V			- 1.8			- 1.8	IIIA	
los‡		$V_{CC} = 5.5 \text{ V},$	V _O = 0	-60		-150	-60		-150	mA	
ICC		$V_{CC} = 5.5 \text{ V},$	See Note 2		10.5	16		10.5	16	mA	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} = 5 V, T _A = 25°C		SN54F74		SN74F74		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	f _{clock} Clock frequency				0	80	0	100	MHz	
	Pulse duration	CLK high, PRE or CLR low	4		4		4		ns	
t _W	ruise duration	CLK low	5		6		5			
	Saturations data hatara CLIVA	High	2		3		2		ns	
t _{su}	Setup time, data before CLK↑	Low	3		4		3			
	Setup time, inactive-state before CLK↑§	PRE or CLR to CLK	2		3		2			
th	Hold time, data after CLK↑	High	1		2		1		ns	
	Holu tille, uata alter CLN	Low	1		2		1			

[§] Inactive-state setup time is also referred to as recovery time.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: ICC is measured with D, CLK, and PRE grounded then with D, CLK, and CLR grounded.

SN54F74, SN74F74 DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH CLEAR AND PRESET SDFS046A – MARCH 1987 – REVISED OCTOBER 1993

switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 \text{ V},$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = 25^{\circ}\text{C}$		V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R_L = 500 Ω, T_A = MIN to MAX† SN54F74 SN74F74				UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			100	145		80		100		MHz
tPLH	CLK	Q or $\overline{\mathbb{Q}}$	3	4.9	6.8	3.8	8.5	3	7.8	ns
^t PHL	CLK		3.6	5.8	8	4.4	10.5	3.6	9.2	115
t _{PLH}	DDE or CLD	PRE or CLR Q or Q	2.4	4.2	6.1	3.2	8	2.4	7.1	ns
^t PHL	FRE OF CLR		2.7	6.6	9	3.5	11.5	2.7	10.5	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 3: Load circuits and waveforms are shown in Section 1.







30-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finisl	h MSL Peak Temp ⁽³⁾
5962-9759201Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9759201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9759201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34101B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34101BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/34101BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN54F74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN74F74D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F74DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74F74N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74F74N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74F74NSR	ACTIVE	SO	NS	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SNJ54F74FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54F74J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54F74W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

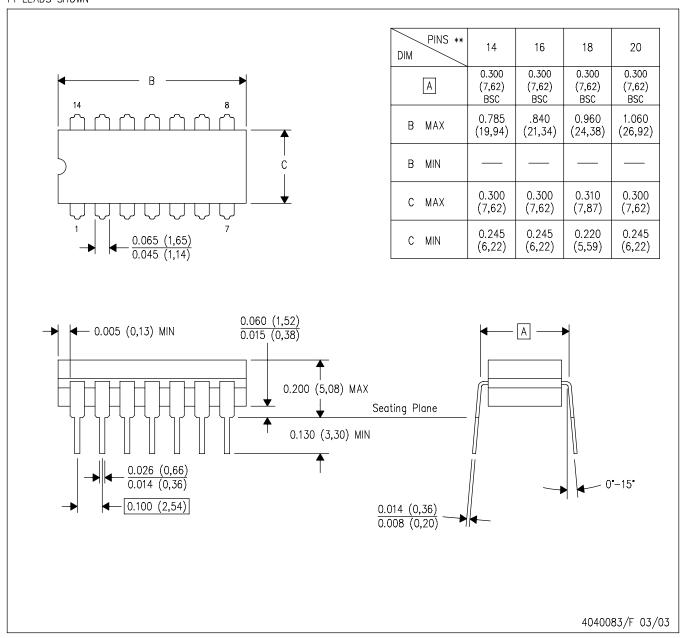
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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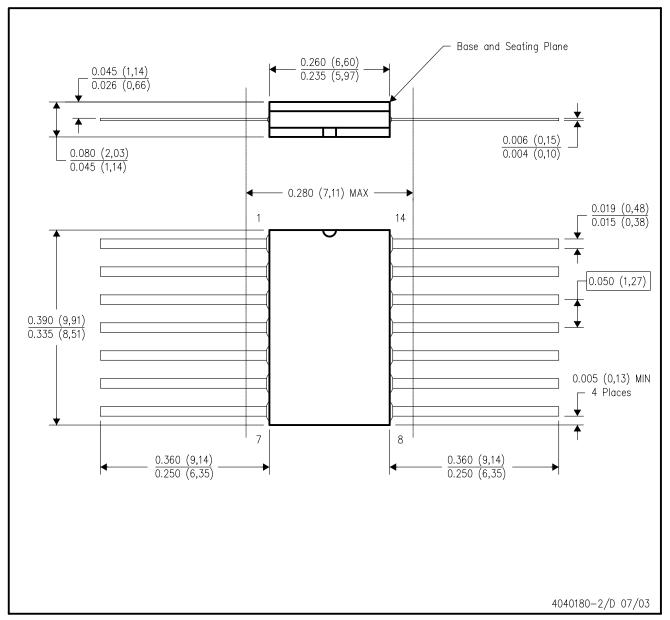
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



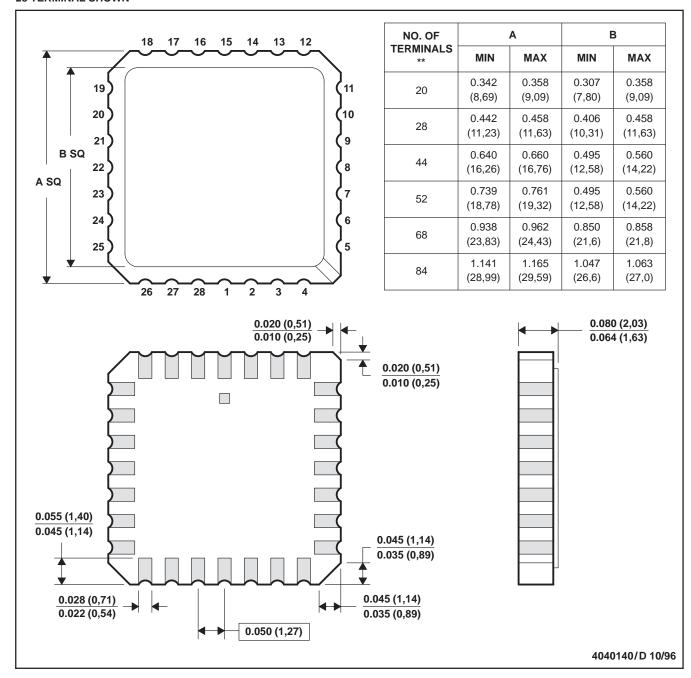
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

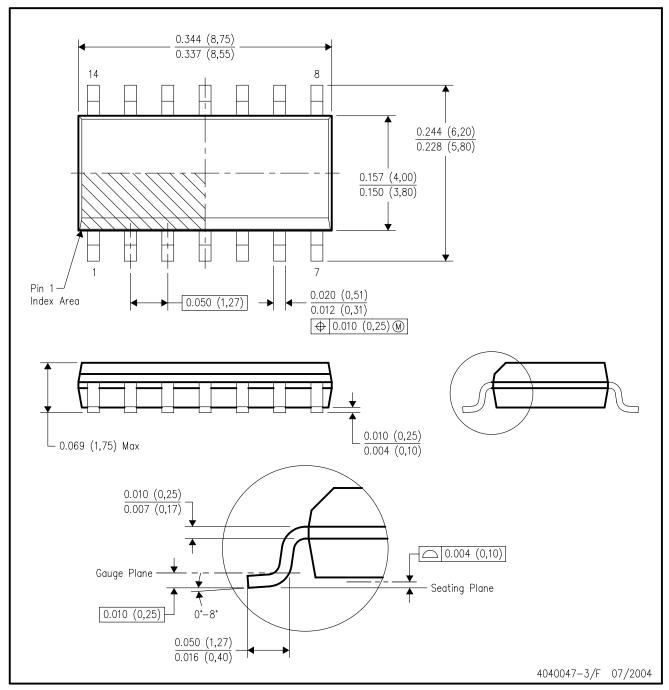


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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